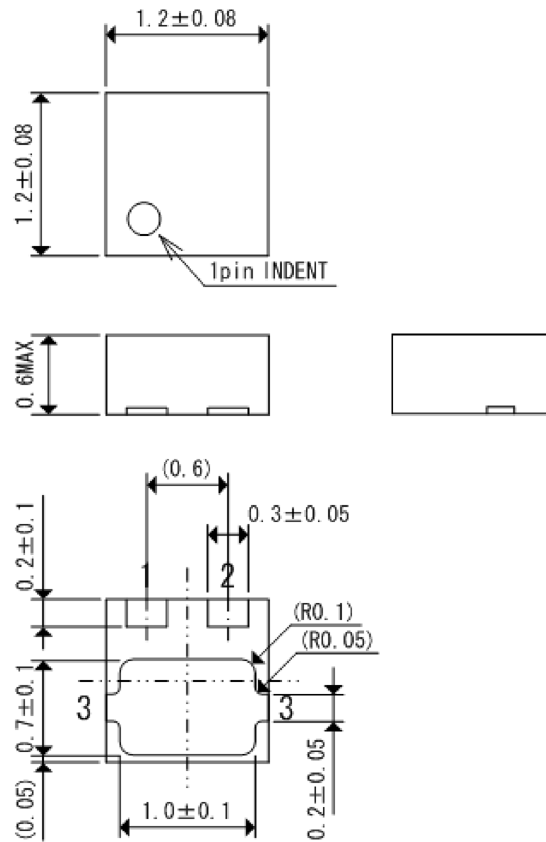
Packaging Information / Reference Pattern Layout Dimensions

●USP-3

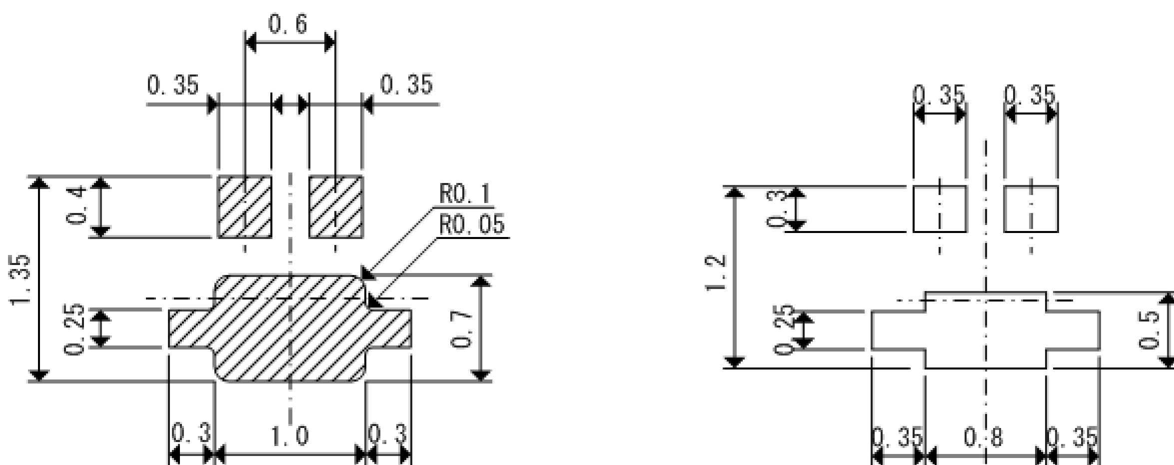
Unit: mm

■Packaging Information



■Reference Pattern Layout Dimension

Note : reference metal mask design

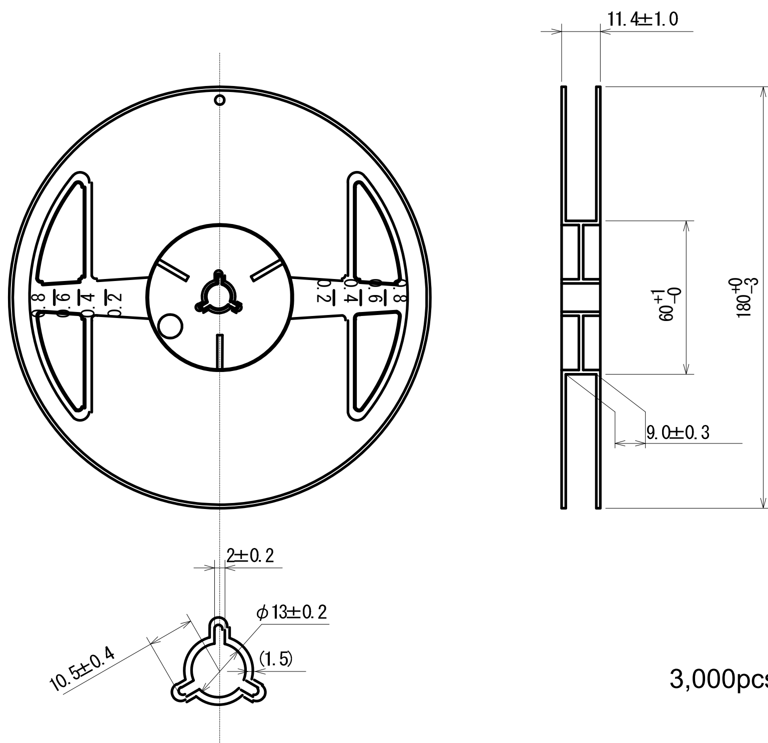


テーピング仕様 / Taping Specifications

USP-3

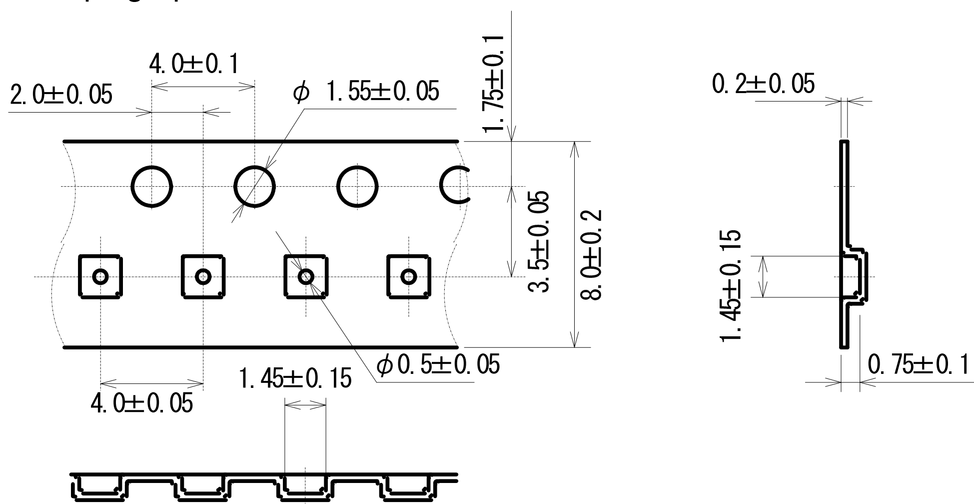
Unit: mm

●リール/Reel

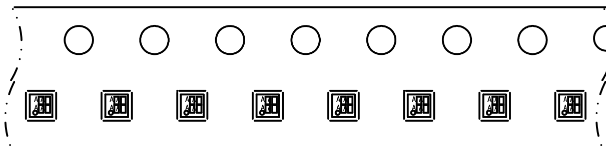


3,000pcs/reel

●テーピング仕様/Taping Specifications



direction of feed



R Type :[Device orientation : Right]

Standard feed

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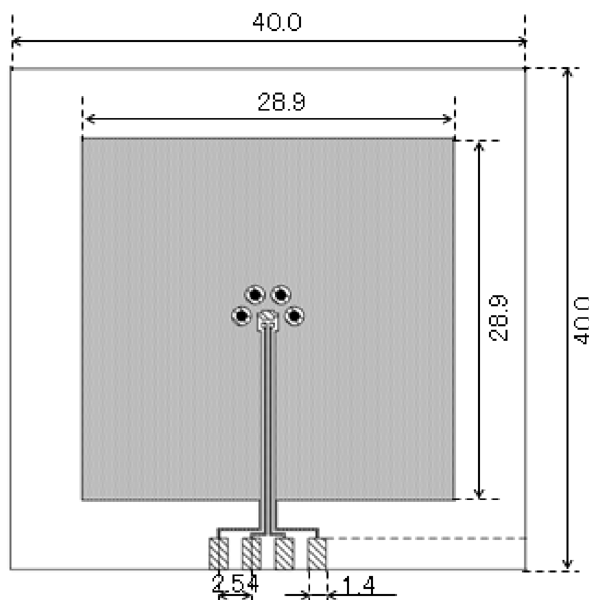
● USP-3 Power Dissipation

Power dissipation data for the USP-3 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board: Dimensions 40 x 40 mm (1600 mm^2 in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
Material: Glass Epoxy (FR-4)
Thickness: 1.6 mm
Through-hole: 4 x 0.8 Diameter

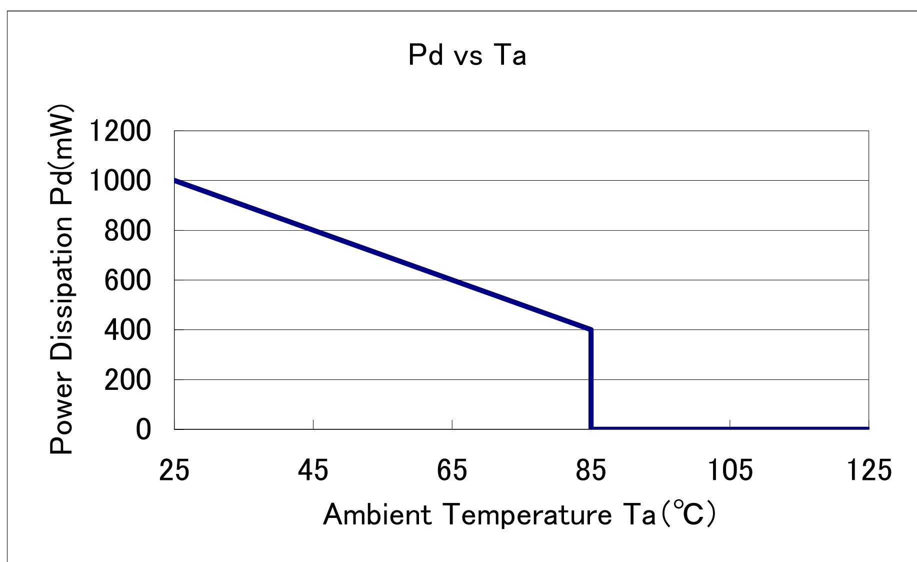


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tj max = 125℃)

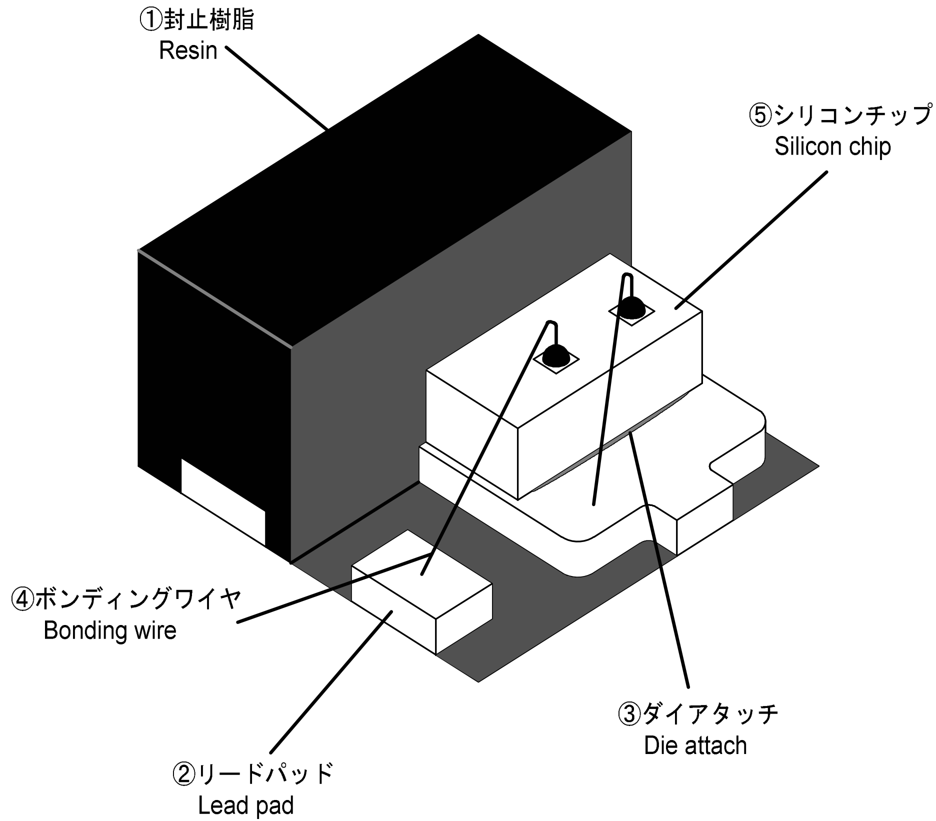
Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance(℃/W)
25	1000	100.00
85	400	



TOREX

USP-3 構造図
USP-3 Perspective

RoHS対応品
RoHS Compliance



項 目 Item		材 料 Material	備 考 Note
①	封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
②	リードパッド Lead pad	ニッケル Nickel	
	端子処理 Inner pad plating	Silverメッキ Silver plating	端子側面は除く Except the side of the terminals.
	端子処理 Outer pad plating	Auメッキ Gold plating	端子側面は除く Except the side of the terminals.
③	ダイアタッチ Die attach	エポキシ Epoxy	
④	ボンディングワイヤ Bonding wire	Au	
⑤	シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking